[Document Name] Abstract

[Title of the Invention] Cleaning Liquid and Cleaning Method for Electronic Material

[Objective] The present invention relates to a cleaning liquid for an electronic material, particularly, a silicon wafer and a cleaning method using the same.

[Means for Solution] The cleaning method according to the present invention is characterized by using ultra-pure water or hydrogen water as raw material water and uses the cleaning liquid in combination with ultrasonic irradiation under presence of hydrogen micro-bubbles.

[Effects] The method of the present invention enables efficient cleaning and removal of particle components and the like on the wafer surface and prevention of re-contamination.

[Selected Drawing] None